

Siconnex BATCHSPRAY® Acid: Efficiency has a name.



Siconnex BATCHSPRAY® Acid is designed for acids and bases. It can be loaded manually or combined with Siconnex BATCHSPRAY® Autoload. The system is completely closed, which means the operator is protected from direct contact with any chemicals. This makes the process safe and also environmentally friendly. Siconnex BATCHSPRAY® Acid can process wafer sizes from 50 mm to 300 mm.



ADVANTAGES

- Automated dry-in, dry-out process
- Five processes possible in one sequence
- Repeatability thanks to process control
- Equipment footprint of 1.2 m x 2 m
- Up to 80% less DI water
- Up to 80% reduction in process media
- Closed system
- User safety
- Chemical mixing management system



BATCHSPRAY®
ACID

ETCH

- Metal Etch (Al, Cu, Ti, Au, Ni,...)
with End Point Detection
- III/V Etch (GaAs, AlGaAs, InGaP,...)
- Oxide Etch
- Freckle Etch
- Silicon Etch
- Ge Etch
- Nitride Etch
- UBM Etch
- Glass Etch

CLEAN

- SicOzone™ Clean
- SicOzone™ + Ultra Diluted Clean Applications
- Contact Cleans
- Organic Removal & Clean
- Etch Residue Clean
- Post Ash Residue Clean
- HF Last
- Prediffusion Cleans
- Field Cleans (Organic & Inorganic Cleans)

RESIST STRIP

- SicOzone™ Strip
- Positive and Negative Resist Strip
- Implanted Photo Resist Strip
- Enhanced Strip
- Resist Rework

DER SICOZONE™-PROZESS

- Cleans and strips resist from substrates.
- No need for expensive solvents that are harmful to health.
- Ozone is cheap to produce from oxygen.